FEATURES

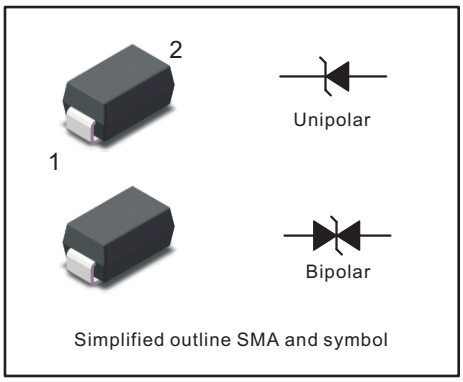
- For surface mounted applications in order to optimize board space.
- Low profile package
- Glass passivated junction
- Low inductance
- Plastic package has Underwriters Laboratory Flammability

MECHANICAL DATA

- Case: SMA
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.055g / 0.002oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Simplified outline SMA and symbol

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation on T_A=25°C (Note 1,2,4, Fig1)	P_{PPM}	400	W
Peak Forward Surge Current (Note 3,Fig 4)	I_{FSM} (UNI)	60	A
Peak Pulse Current on 10/1000 us waveform (Note 1, Fig 3)	I_{PPM}	see Table 1	A
ESD Voltage per IEC6100-4-2 Contact Air	V_{ESD1} V_{ESD2}	±30 ±30	kV
Typical Thermal Resistance Junction to Ambient(Note 2)	$R_{\theta JA}$	30	°C/W
Operating Junction Temperature and Storage Temperature Range	T_j, T_{stg}	-65 ~ +150	°C

NOTES:

1. Non-repetitive current pulse, per Fig.3 and derated above T_A = 25°C per Fig. 2.
2. Mounted on 5mm^2 copper pads to each terminal.
3. Peak Forward Surge Current : 8.3ms single half sine-wave Superimposed on rated load (JEDEC method).
4. Peak pulse power waveform is 10/1000μS.

Characteristics at Ta = 25°C

Type	Reverse Stand-off Voltage	Breakdown Voltage		Test Current	Reverse Leakage	Max. Clamp Voltage	Peak Pulse Current	Package
		V_{BR} @ I_T						SMA
	V_{RRM}	Min	Max	I_T	I_R @ V_{RRM}	V_C @ I_{PP}	I_{PP}	Device Marking Ccode
BI	V	V	V	mA	μA	V	A	BI
BS0150MS	15	16.7	18.5	1	1	24.4	16.4	XM

Fig.1 Peak Pulse Power Rating Curve

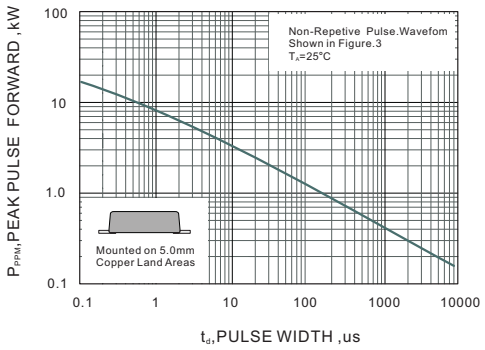


Fig.2 Forward Current Derating Curve

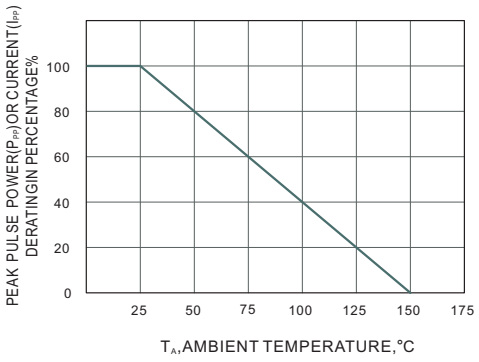


Fig.3 Pulse Waveform

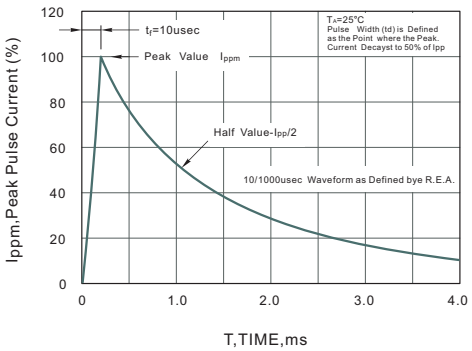
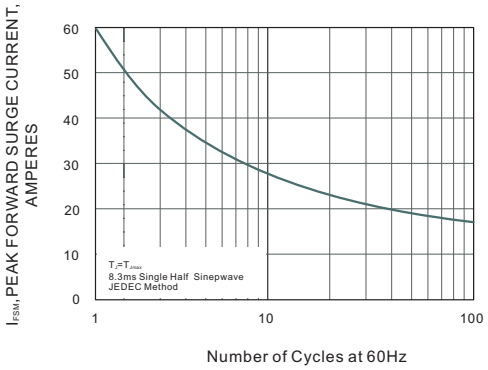


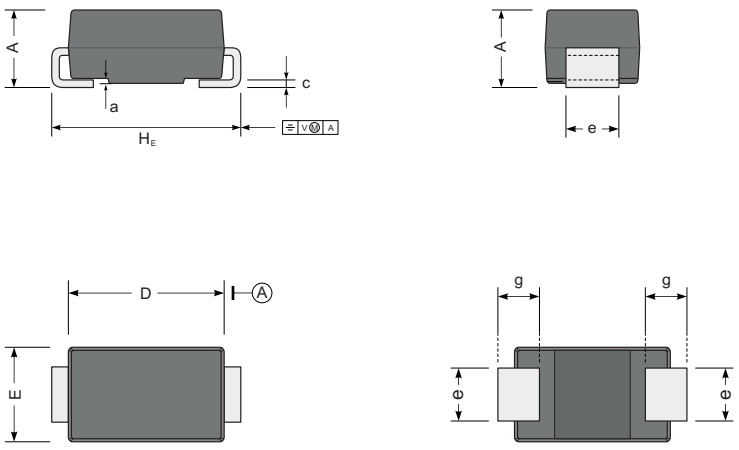
Fig.4 Maximum Non-Repetitive Peak Forward Surge Current



PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMA



UNIT		A	D	E	H_E	c	e	g	a
mm	max	2.2	4.5	2.7	5.2	0.31	1.6	1.5	0.3
	min	1.9	4.0	2.3	4.7	0.15	1.3	0.9	
mil	max	87	181	106	205	12	63	59	12
	min	75	157	91	185	6	51	35	

The recommended mounting pad size

